规格书编号 ：

SPEC NO : HDF1250A8S4SP00

产品规格书
SPECIFICATION

CUSTOMER 客 户：

PRODUCT 产 品：SAW FILTER

MODEL NO 型 号：HDF1250A8-S4

MARKING 印 字：HDF4G358

PREPARED 编 制：张莉 CHECKED 审 核：王勇

APPROVED 批 准：王勇 D A T E 日 期：2013-7-30

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司

Shoulder Electronics Limited

更改历史记录
History Record

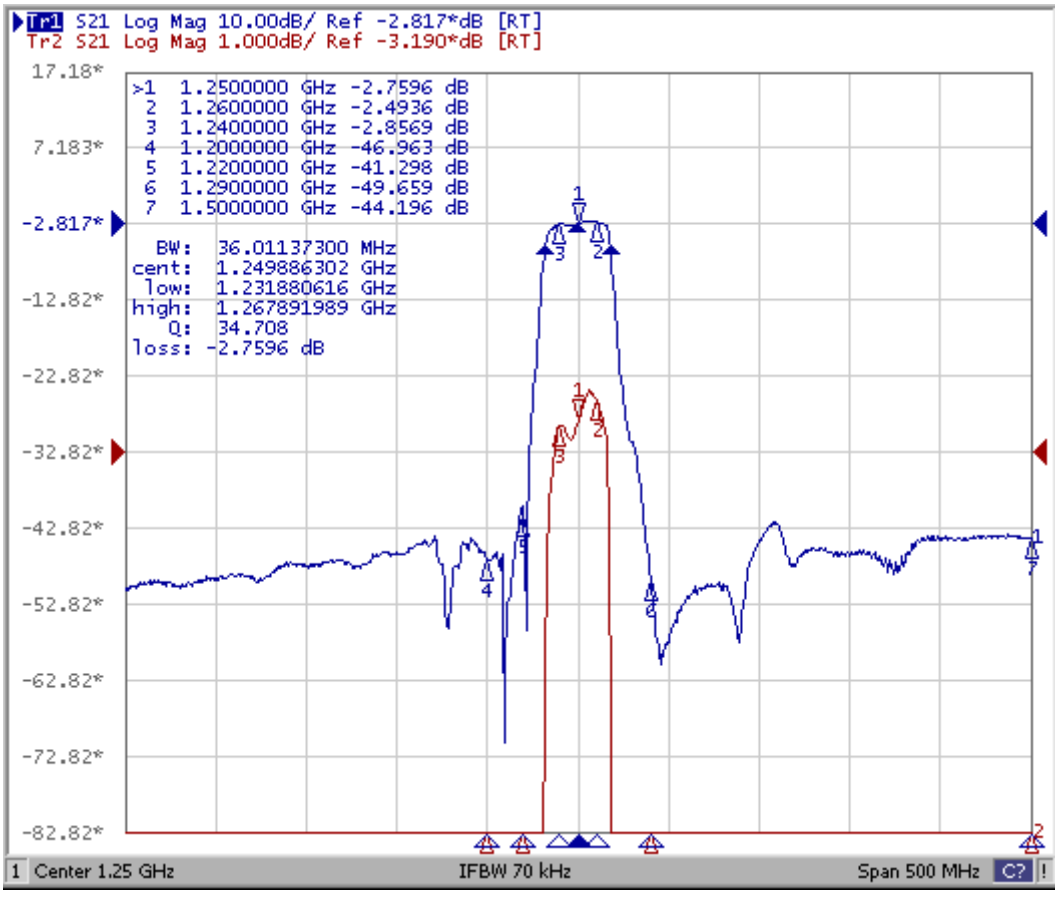
更改日期 Date	规格书编号 Spec. No.	产品型号 Part No.	客户产品型号 Customer No.	更改内容描述 Modify Content	备注 Remark

1. ELECTRICAL SPECIFICATION

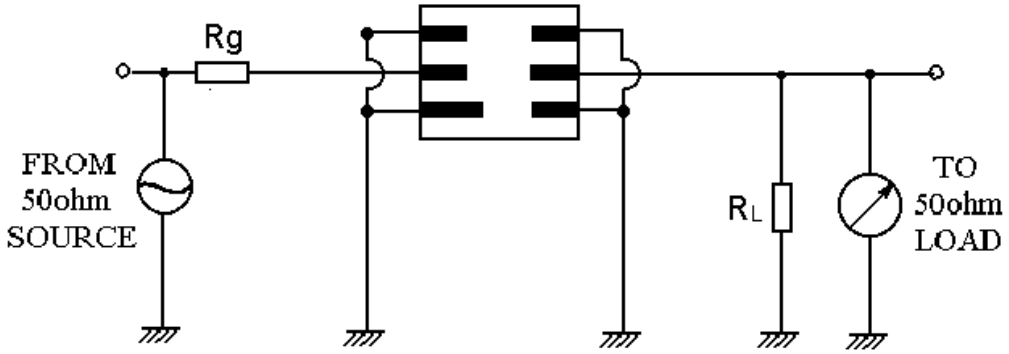
Maximum Input Power	+10dBm
DC voltage	10V
Storage Temperature Range	-45℃ to +85℃
Operation Temperature Range	-40℃ to +85℃

Electronic Characteristics

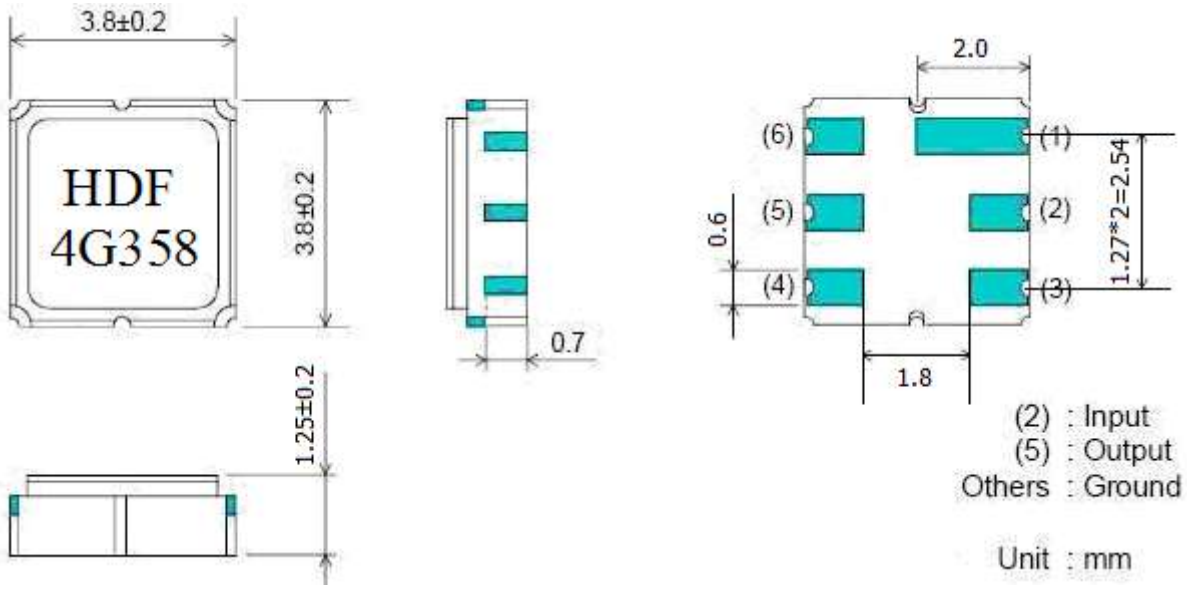
	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	1250	-
Insertion Loss (1250 MHz)	dB		2.0	3.5
Amplitude Ripple(1250±10 MHz)	dB		0.9	2.0
Absolute Attenuation 10 ~ 1200 MHz 1200 ~ 1220 MHz 1290 ~ 1500 MHz	dB	 40 30 40	 50 35 45	-
Input/Output Impedance	Ohms		50	



2. TEST CIRCUIT



3. DIMENSION



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -45℃ for 30 minutes. Following by a high temperature of +25℃ for 5 Minutes and a higher temperature of +85℃ for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260℃±5℃ for 10±1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at 245℃ ±5℃ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration &destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.